IN-MAT TECHNOLOGIES®

TECHNICAL DATA SHEET **Nov'21 Rev 1.7**

IMT-SA110-2
SURFACE MOUNT ADHESIVE

IMT-SA110-2 is a single component, surface mount epoxy adhesive formulated to bond chips or components onto printed circuit boards. IMT-SA110-2 possesses excellent dispensing rhelogy and has a wide curing window. This SMT adhesive offers excellent heat and chemical resistance as well as exhibits good adhesion property to PC boards.

IMT-SA110-2 is solventless, 100% solid system and does not contains hazardous and/or prohibited substances. It complies to RoHS3, EU directive 2015/863, Substances of Very High Concern (SVHC) published by ECHA as well as Halogen Free.

This SMT adhesive is designed for dispensing application.

TYPICAL PROPERTIES*

Cure Conditions	1. 150°C for 60s 2. 130°C for 5mins 3. 110°C for 15mins

Physical Properties

Color	Red before and after cure
Consistency	Thixotropic paste
Specific Gravity	1.14
Viscosity @10rpm, 25°C	23,000cPs
TI Index (1/10rpm), 25°C	5.0
Solid Content	100%
Glass transition temperature	> 130°C
Shore D Hardness	90
Die Shear Strength	> 10Kgf per 3.5 x 2mm die on FR4 substrate
Volume Resistivity	> 1 x 10**14Ωcm
Operating Temperature	-40°C to above 150°C

Ionic Contents

Chloride, Cl-	≤ 500ppm
Bromine, Br-	Not detected
PVC	Not detected

Pot Life	1 week at room temperature
Shelf Life	12 months at 0°C or below

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* The information is based on data and tests believed to be accurate. In-Mat Technologies (S) Pte Ltd makes no warranties as to its accuracy and assumes no liability in connection with the use or inability to use this product.